

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|--------------------|-------------|-----|-----|----------|----------------------|
| PEAK WAVELENGTH | | 585 | | nm | |
| FORWARD VOLTAGE | | 2.1 | 2.5 | V_f | |
| REVERSE VOLTAGE | 5.0 | | | V_r | $I_f=100\mu\text{A}$ |
| AXIAL INTENSITY | | 10 | | med | $I_f=20\text{mA}$ |
| VIEWING ANGLE | | 90 | | 2x theta | |
| EMITTED COLOR: | YELLOW | | | | |
| EPOXY LENS FINISH: | WATER CLEAR | | | | |

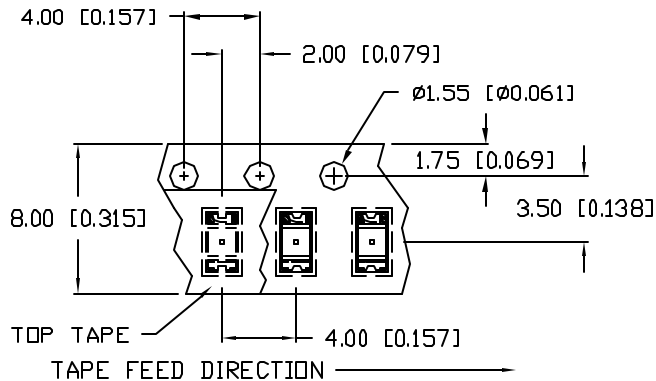
LIMITS OF SAFE OPERATION AT 25°C

| PARAMETER | MAX | UNITS |
|-----------------------|------------|-------|
| PEAK FORWARD CURRENT* | 160 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 100 | mW |
| DERATE FROM 25°C | -1.2 | mW/°C |
| OPERATING TEMP. | -40 TO +85 | °C |
| STORAGE TEMP. | -40 TO +85 | °C |

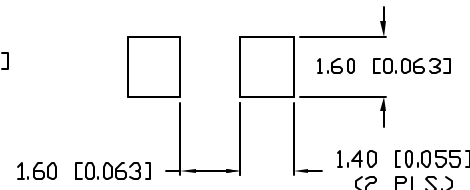
* $t < 10\mu\text{s}$

NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



RECOMMENDED SOLDER PAD LAYOUT



CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030), MIN= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

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| 3mm x 1.5mm SURFACE MOUNT LED WITH LENS, 585nm YELLOW LED, WATER CLEAR LENS, TAPE AND REEL | | RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS. | DRAWN BY: JD CHECKED BY: APPROVED BY: DATE: 9.16.04 PAGE: 1 OF 1 SCALE: N/A |